

AMENDMENTS TO THE CLAIMS

Please cancel claims 4 and 7-10, as set forth in the listing of claims that follows:

Listing of Claims

(insert attached listing of marked-up claims)

1. (Previously Amended) An integrated circuit package,
comprising:
 - a first non-conductive substrate having a first inner surface;
at least one first contact pad disposed on said first inner surface for
selective electrical communication with circuit elements through conductors carried by
said first substrate;
 - a second non-conductive substrate having a second inner surface;
at least one second contact pad disposed on said second inner surface for
selective electrical communication with circuit elements through conductors carried by
said second substrate, wherein said first and second contact pads are opposed from one
another;
 - a die disposed between said first and second inner surfaces, said die
having a first thickness; and
 - a leadframe including a member having a proximal end and a distal end,
said proximal end having a second thickness less than said first thickness, said distal end
being disposed between said first and second inner surfaces, said distal end being
undulated such that said distal end has an effective thickness greater than said second
thickness to effect bridging of said opposed contact pads.

2. (Original) The package of claim 1, wherein said effective thickness is approximately equal to said first thickness.

3. (Original) The package of claim 1, wherein said distal end is one of offset formed, squirt formed, corrugated formed, and embossed formed.

4. (Canceled)

5. (Previously Amended) The package of claim 1, wherein said at least one first contact pad comprises at least one first bonded copper element, said at least one second contact pad comprises at least one second bonded copper element.

6. (Previously Amended) The package of claim 1, further comprising:

at least one first layer of conductive attachment material disposed between said at least one first contact pad and each of said distal end of said member and said die; and

at least one second layer of conductive attachment material disposed between said at least one second contact pad and each of said distal end of said member and said die.

7. (Canceled)

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Canceled)

USSN 10/780,163 filed 02/17/2004 (DP-310331)
Amendment dated: 02-AUG-2006
Response to Office Action of 07/24/2006

14. (Canceled)
15. (Canceled)
16. (Canceled)
17. (Canceled)
18. (Canceled)
19. (Canceled)
20. (Canceled)